# 562/564 Series

Circuit Board Mount Blocks for TE5/TR5 Type Fuses

## RoHS





564 Series Holder

## **Additional Information**



Resources 562 Series



Resources 564 Series



Accessories 564 Series



Samples 562 Series



Samples 564 Series



	562 Series	564 Series	
<b>Compatible Fuses</b>	TR5/TE5		
Materials	Block: Black Thermoplastic, UL94 V-0 PET		
	Terminals: Copper alloy; solderable tinned		
Electrical Data (0000)	Rated Voltage: 250V		
Electrical Data (23°C)	Max. Current/Power: 6.3A/1.6W		
Mounting	PC Board,	PC Board,	
	5.08mm pin spacing	5.08mm pad spacing	
Minimum Cross	Conducting path -	Conducting path -	
Section	0.1mm <sup>2</sup>	0.1mm <sup>2</sup>	
Unit Weight	0.12g	0.44g	
Ambient Temperature	- 40°C to + 85°C		

#### **Ordering Information**

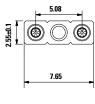
Ordering Number	Circuit Board Mounting	Packaging
56200001009	Thru-Hole	1000 (Bulk pack)
56400001009	Surface Mount	1500 (Tape /Reel)

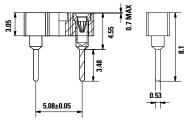
#### Agency Approvals

Agency	Agency File Number	
	562 Series	564 Series
<b>71</b>	E14721	E14721

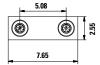
### Dimensions units in mm

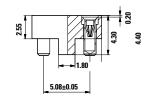
#### 562 Series Holder



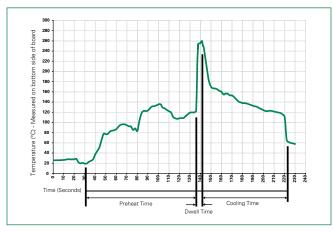


564 Series Holder





## Soldering Parameters - Wave Soldering



## Soldering Parameters - Reflow Soldering

Reflow Condition		Pb - Free assembly
Number of allowed reflow cycles		3
Pre Heat	-Temperature Min (T <sub>s(min)</sub> )	150°C
	-Temperature Max (T <sub>s(max)</sub> )	200°C
	-Time (Min to Max) (t <sub>s</sub> )	60 - 120 Secs.
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak		5°C/second max.
T <sub>s(max)</sub> to T <sub>L</sub> - Ramp-up Rate		5°C/second max.
Reflow	- Temperature ( $T_L$ ) (Liquidus)	217°C
	-Temperature (t <sub>L</sub> )	60 - 150 seconds
Peak Temperature (T <sub>P</sub> )		240 <sup>+/-5</sup> °C
Time within 5oC of actual peak Temperature ( $t_{\rm p}$ )		30 secs. max.
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T <sub>P</sub> )		8 minutes max.
Do not exceed		245°C

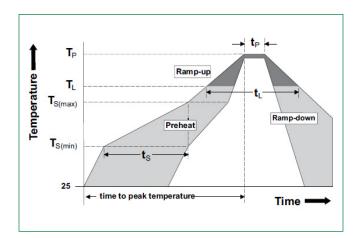
#### **Recommended Process Parameters:**

Wave Parameter	Lead-Free Recommendation	
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)	
Temperature Minimum:	100°C	
Temperature Maximum:	150°C	
Preheat Time:	60-180 seconds	
Solder Pot Temperature:	260°C Maximum	
Solder Dwell Time:	2-5 seconds	

#### **Recommended Hand-Solder Parameters:**

Solder Iron Temperature: 350°C +/- 5°C

Heating time: 5 seconds max **Note:** These devicess are not recommended for IR and Convection Reflow process



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